

Type number	Package	Package description	Total product weight
74HC2G08DC	SOT765-1	VSSOP8	9.98163 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935274803125	11	1	260	30 s	1	240	20 s	3	Bangkok, Thailand; Ayutthaya, Thailand; Suzhou, China; Nijmegen, Netherlands	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.02871	80.10000	0.28761
		Polymer	Resin system	Proprietary	0.00713	19.90000
			subTotal		0.03584	100.00000
Die	Doped silicon	Silicon (Si)	7440-21-3	0.13079	100.00000	1.31035
				subTotal	0.13079	100.00000
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	3.39855	97.00000	34.04805
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.10511	3.00000	1.05303
				subTotal	3.50366	100.00000
Mould Compound	Additive	Non hazardous	Proprietary	0.29057	4.70000	2.91103
	Filler	Silica fused	60676-86-0	4.88402	79.00000	48.93005
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	0.37094	6.00000	3.71621
	Pigment	Carbon black	1333-86-4	0.01236	0.20000	0.12387
	Polymer	1,4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	0.24729	4.00000	2.47747
		Non hazardous	Proprietary	0.25347	4.10000	2.53941
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.12365	2.00000	1.23874
		subTotal	6.18230	100.00000	61.93678	
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00309	3.00000	0.03094
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.09502	92.30000	0.95198
		Palladium (Pd)	7440-05-3	0.00319	3.10000	0.03197
		Silver (Ag)	7440-22-4	0.00165	1.60000	0.01650
				subTotal	0.10295	100.00000
Wire	Pure metal	Copper (Cu)	7440-50-8	0.02608	100.00000	0.26133
				subTotal	0.02608	100.00000

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.